

*In the Claims*

Please add new claim 17 as follows:

17. (newly added) A microelectronic fabrication comprising:

a substrate;

a spirally patterned conductor layer formed over the substrate, wherein the spirally patterned conductor layer terminates in a microelectronic structure formed within the center of the spirally patterned conductor layer, wherein the spirally patterned conductor layer forms a planar spiral inductor, and wherein the microelectronic structure formed within the center of the spirally patterned conductor layer comprises a series of electrically interconnected sub-patterns; and

a bond wire bonded upon the microelectronic structure, wherein the bond wire has incorporated therein a plurality of loops.